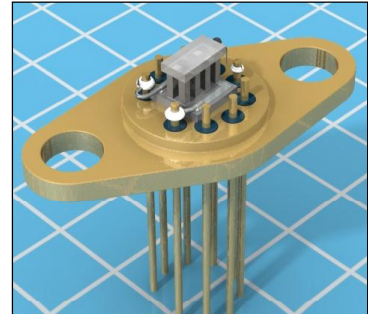


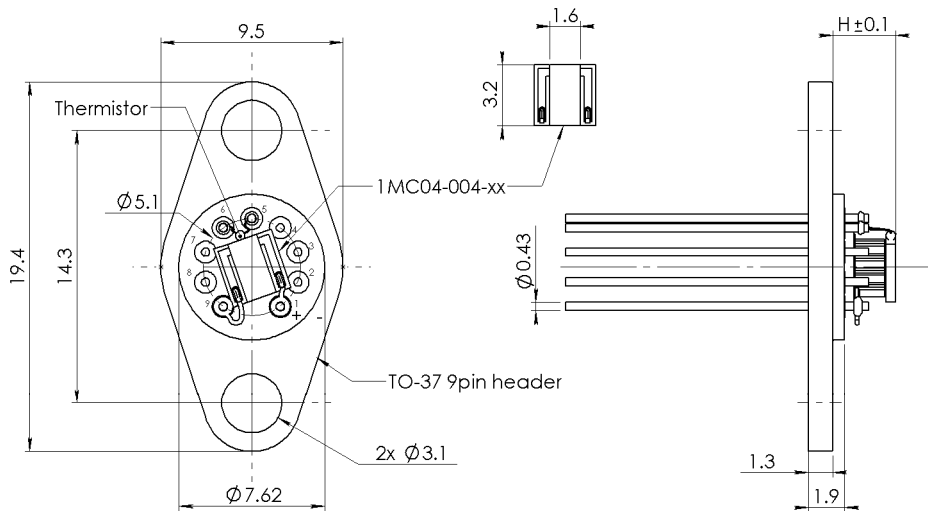
Performance parameters TO3709.1MC04004xx

| Mounted TEC Type | DT <sub>max</sub> , K | Q <sub>max</sub> , W | I <sub>max</sub> , A | U <sub>max</sub> , V | H, mm | R <sub>t</sub> , K/W |
|------------------|-----------------------|----------------------|----------------------|----------------------|-------|----------------------|
| 1MC04-004-05     | 69                    | 0.41                 | 1.4                  | 0.49                 | 1.6   | 4.75                 |
| 1MC04-004-08     | 71                    | 0.27                 | 0.9                  |                      | 1.9   |                      |
| 1MC04-004-10     | 71                    | 0.22                 | 0.7                  |                      | 2.1   |                      |
| 1MC04-004-12     | 71                    | 0.18                 | 0.6                  |                      | 2.3   |                      |
| 1MC04-004-15     | 71                    | 0.15                 | 0.5                  |                      | 2.6   |                      |

Performance data are given for  $T_{hot}=300K$  vacuum



Technical Drawing



Ordering Options

**A. Header material**

Kovar

**B. Header finish**

1. Gold plating
2. Ni plating

**C. TEC Mounting**

1. Soldering
  - 1.1 Solder 117 (InSn,  $T_{melt}=117^{\circ}C$ )
  - 1.2 Solder 138 (SnBi,  $T_{melt}=138^{\circ}C$ )
  - 1.3 Solder 183 (PbSn,  $T_{melt}=183^{\circ}C$ )
  - 1.4 Solder 199 (SnZn,  $T_{melt}=199^{\circ}C$ )
2. Epoxy gluing

**D. TEC Leads Connection**

Solder 230 (SnSb,  $T_{melt}=230^{\circ}C$ )

**E. TEC Ceramics**

1. Pure  $Al_2O_3$  (100%) - standard
2. Alumina ( $Al_2O_3$  - 96%) - optional
3. Aluminum Nitride (AlN) - optional

**F. TEC Cold Side Finish**

1. Clear ceramics
2. Metallized
  - 2.1 Ni / Sn(Bi)
  - 2.2 Gold plating
3. Metallized and Pre-tinned
  - 3.1 Solder 94 (PbSnBi,  $T_{melt}=94^{\circ}C$ )
  - 3.2 Solder 117 (InSn,  $T_{melt}=117^{\circ}C$ )
  - 3.3 Solder 138 (SnBi,  $T_{melt}=138^{\circ}C$ )
  - 3.4 Solder 183 (PbSn,  $T_{melt}=183^{\circ}C$ )
  - 3.5 Solder 199 (SnZn,  $T_{melt}=199^{\circ}C$ )

**G. Thermistor (optional)**

NTC thermistor type TB  
Resistance nominal  
1. 2.2 kOhm@20C  
2. 10.0 kOhm@20C

Individual calibration is available in -65..+85°C

**H. Thermistor Mounting**

Epoxy Gluing

**I. Thermistor Leads Connect**

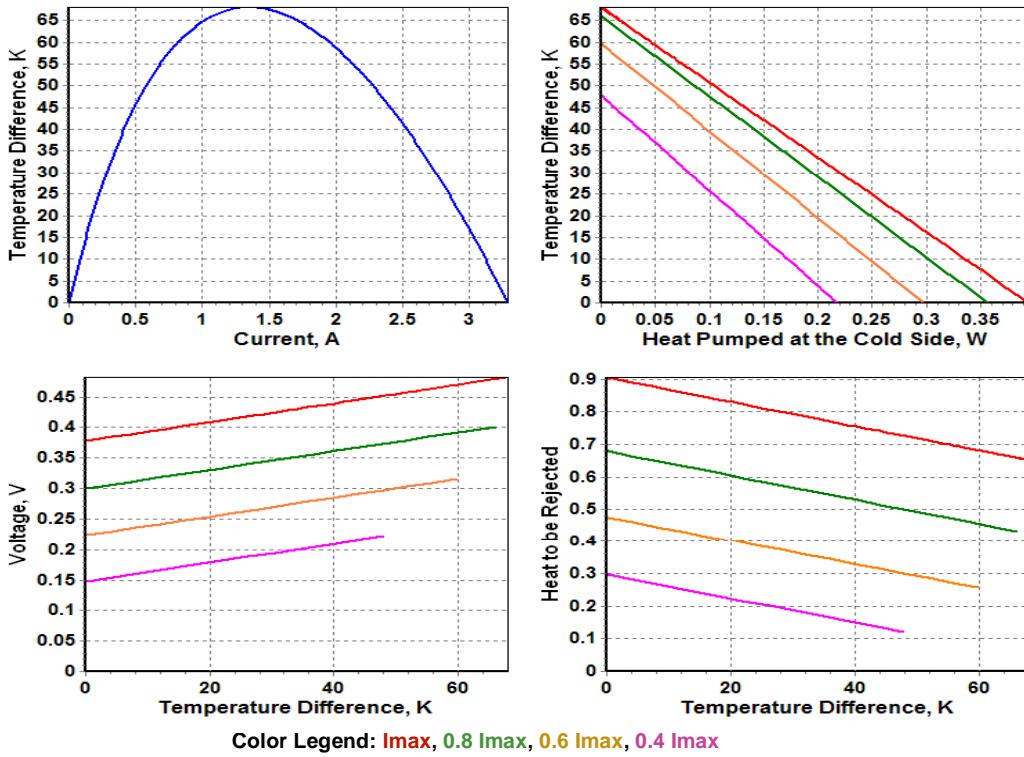
Solder 230 (SnSb,  $T_{melt}=230^{\circ}C$ )

**J. Pinout configuration**

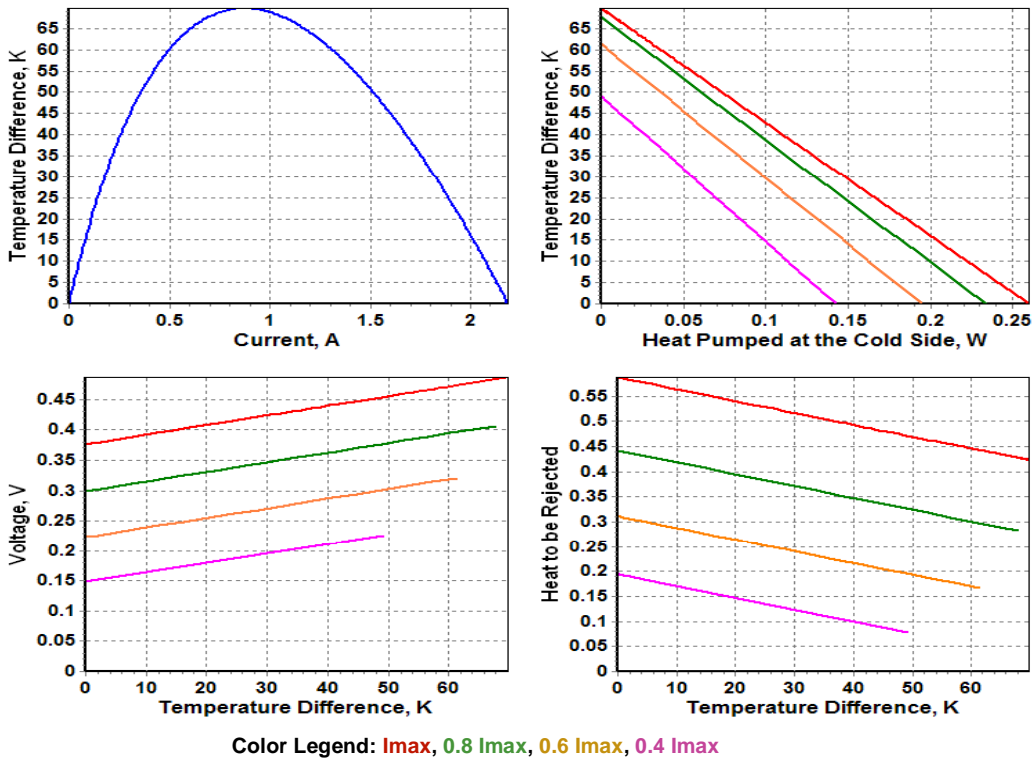
Can be specified by customer

Thermoelectric Sub-mount Datasheet RMT Ltd.

TO3709.1MC0400405 Standard Performance Plots



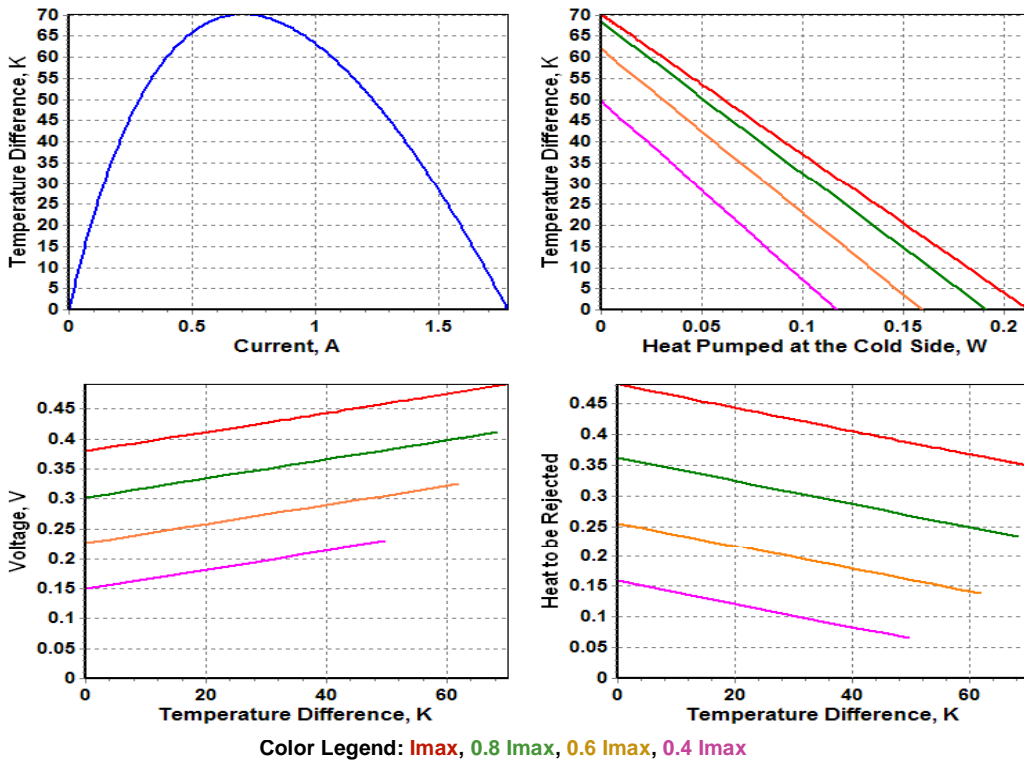
TO3709.1MC0400408 Standard Performance Plots



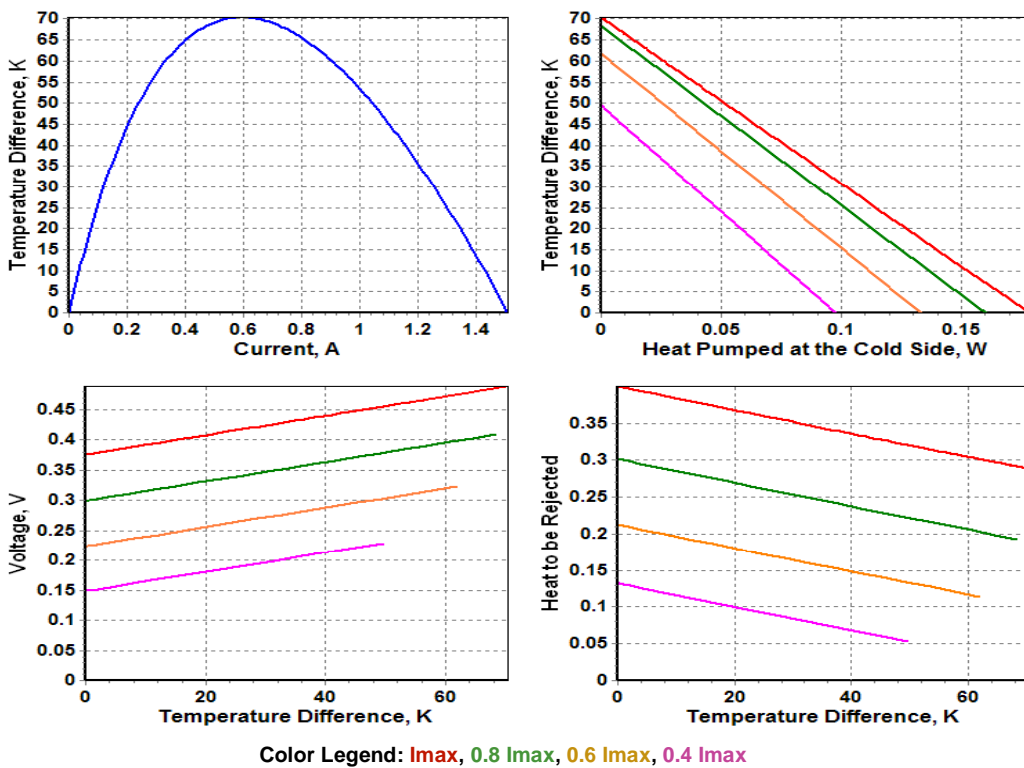
Performance plots are created with TECCAD Software. TECCAD is available for download from RMT Ltd. website - [www.rmtltd.ru](http://www.rmtltd.ru)

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TO3709.1MC0400410 Standard Performance Plots



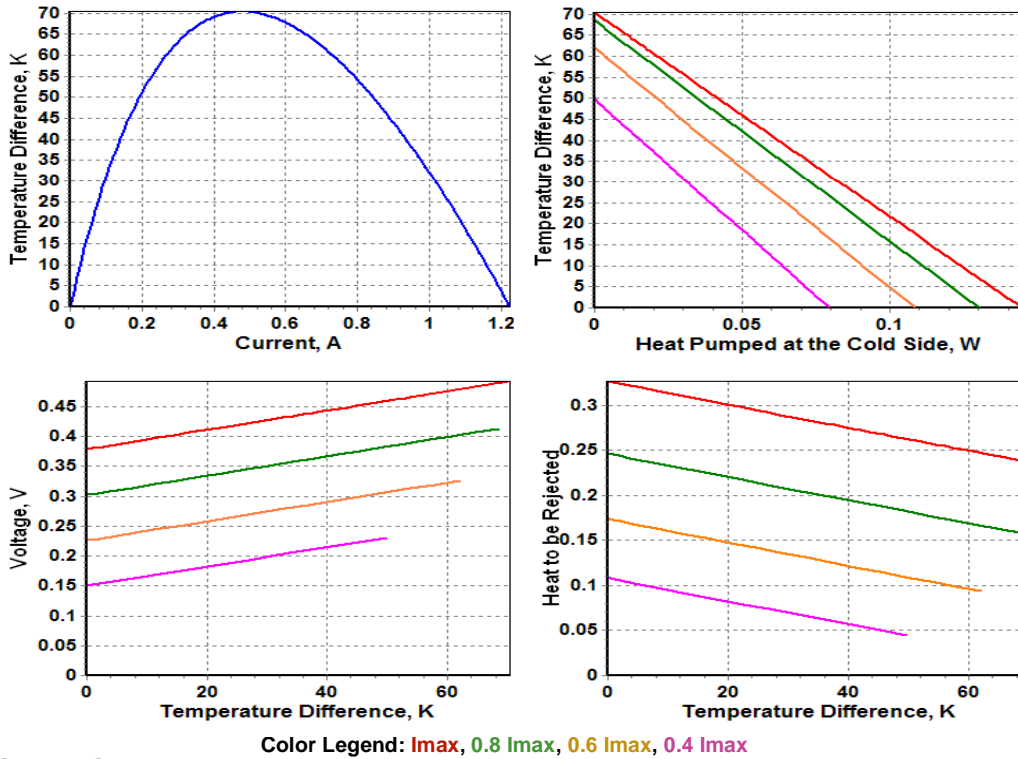
TO3709.1MC0400412 Standard Performance Plots



Performance plots are created with TECCAD Software. TECCAD is available for download from RMT Ltd. website - [www.rmtltd.ru](http://www.rmtltd.ru)

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TO3709.1MC0400415 Standard Performance Plots



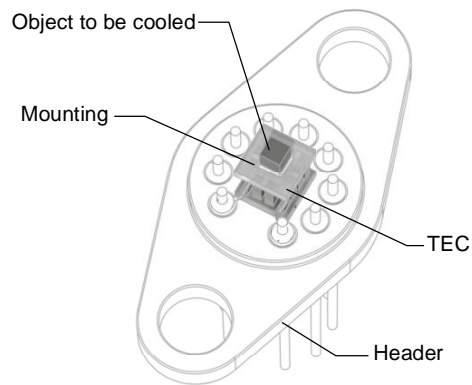
**Applications Tips**

**Cautions**

- Do not heat TE module more than 200°C (TEC assembled at 230°C) or 160°C (TEC assembled at 183°C).
- Do not use TE module without attached heat sink at hot (bottom) side.
- Connect TE sub-mount to a DC power supply in accordance to polarity.
- Do not apply DC current higher than  $I_{max}$ .

**Installation**

- Soldering of object to be cooled.  
Method suitable for a TE module with the metallized cold side (Ordering Options. Item F). Soldering requires careful procedures:
  - Never overheat TEC (Cautions. Item 1).
  - Use solder with melting point less than TEC mounting solder (Ordering Options. Item C).
- Gluing of object to be cooled.  
Method available by glues with good thermoconductive properties. Not recommended for high vacuum applications and long operations at high temperature.



**Definitions**

| Value            | Description                                   | Notes  |
|------------------|---|--|
| $\Delta T_{max}$ | Maximum temperature difference at $I=I_{max}$ | rated at $Q_{max}=0$ , at other $Q$ it should be estimated as $\Delta T = \Delta T_{max}(1 - Q/Q_{max})$         |
| $Q_{max}$        | Maximum heat pumping capacity at $I=I_{max}$  | rated at $\Delta T=0$ , at other $\Delta T$ it should be estimated as $Q = Q_{max}(1 - \Delta T/\Delta T_{max})$ |
| $I_{max}$        | Maximum current                               | Electric parameters resulting in greatest $\Delta T_{max}$   |
| $U_{max}$        | Maximum voltage drop                          |  |
| $R_t$            | Header thermal resistance                     |  |
| -xx              | Thermoelectric pellet length code             | Pellet length is "-xx" x 10 (in mm)  |
| $T_{hot}$        | TEC hot side temperature                      | Performance data shown in specifications are given for $T_{hot}=300$ K, vacuum                                   |
| H                | Total TEC height                              | All dimensions are given in mm   |